Silicon Step Recovery Diodes



MMDx & SMMDx Series

Rev. V5

Features

- Output Combs to 40+ GHz
- Transition Times down to 35 ps
- Screening per MIL-PRF-19500 and MIL-PRF-38534 available

Description

The diodes feature fully passivated, true mesa construction for sharp transitions and improved stability. The beam lead SRDs have the industry's fastest transition times for millimeter wave multiplication and picoseconds pulse forming.







Chip & Beam Lead Electrical Specifications: T_A = 25°C

Model	Voltage Breakdown (V _B)	Capac	ction citance C _J)	Lifetime (t)		Transition Time (t _t)		Frequency Cutoff (F _{co})	Theta (θ _{JC})
	V	pF		ns		ps		GHz	°C/W
	Min.	Min.	Max.	Min.	Тур.	Тур. Мах.		Тур.	Max.
Chip									
MMD805-C12	60	2.5	3.5	80	100	250	300	130	15
MMD810-C12	50	1.5	2.5	40	70	200	250	200	22
MMD820-C12	40	1.0	1.7	30	60	80	100	390	25
MMD830-C11	25	0.5	1.0	15	30	60	80	700	45
MMD832-C11	20	0.4	0.8	10	15	60	80	660	50
MMD835-C11	15	0.3	0.7	10	20	60	70	800	60
MMD837-C11	20	0.2	0.4	5	10	60	70	1300	60
MMD840-C11	15	0.2	0.4	7	15	60	70	880	60
Beam Lead									
MMDB30-B11	14	0.15	0.25	1	4	30	38	530	600
MMDB35-B11	16	0.13	0.20	1	4	35	45	482	600
MMDB45-B11	25	0.11	0.20	3	8	45	58	410	600

Test Conditions:

 $V_B: I_R = 10 \mu A$

 C_J : $V_R = 6 \dot{V}$, 1 MHz

t: $I_F = 10 \text{ mA}$, $I_R = 6 \text{ mA} @ 50\%$ Recovery

 t_t : for Chip: $I_F = 10 \text{ mA}$, $V_R = 10 \text{ V}$

 t_t : for Beam Lead: $I_F = 3$ mA, $V_R = 7$ V

F_{CO}: 1/2πR_S

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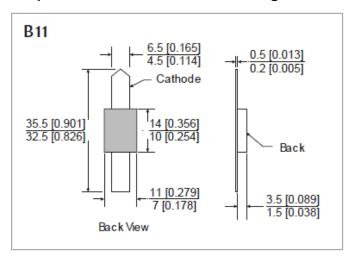


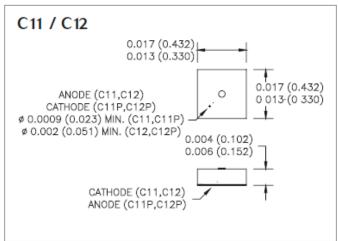
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Absolute Maximum Ratings

Parameters	Rating
Reverse Voltage	Rated V _{BR}
Forward Current	Chip = 150 mA Beam Lead = 50 mA
CW Power Dissipation	150°C / θ _{JC} @ +25°C, derate linearly to zero @ T _{HSK} = +175°C
Operating / Storage Temperature	-65°C to +175°C
Mounting / Bonding Temperature	Chip = +310°C for 30 seconds Beam Lead = +235°C for 10 seconds

Chip & Beam Lead Outline Drawings







Rev. V5

Ceramic Packaged Electrical Specifications: T_A = 25°C

Model	Voltage Breakdown (V _B)	Capac	tal itance t _T)	Lifetime (t)		Transition Time (t _t)		Package
	V	р	F	r	ıs	ps		
	Min.	Min.	Max.	Min.	Тур.	Тур.	Max.	
		2.57	3.57					E25
		2.58	3.58	80				E28 / 28X
MMD805-	60	2.68	3.68		100	250	300	H20
WIWID003-	00	2.68	3.68	00	100	250	300	T86
		2.75	3.75					T89
		2.56	3.56					0805-2
		1.58	2.58				250	E28 / 28X
MMD810-	50	1.68	2.68	40	70	200		H20
IVIIVIDO 10-	30	1.68	2.68	40	70	200		T86
		1.75	2.75					T89
		1.08	1.78		60	80	100	E28 / 28X
MMD820-	40	1.18	1.88	30				H20
IVIIVID620-	40	1.18	1.88	30		00		T86
		1.06	1.76					0805-2
		0.58	1.08					E28 / 28X
MMD830-	25	0.68	1.18	15	30	60	80	H20
IVIIVIDO3U-	25	0.68	1.18	13	30	60	00	T86
		0.56	1.06					0805-2
		0.48	0.88					E28 / 28X
MMD832-	20	0.58	0.98	10	15	60	80	H20
IVIIVIDO32-	20	0.58	0.98	10	15	00	00	T86
		0.46	0.86					0805-2
		0.38	0.88					E28 / 28X
MMDose	15	0.42	0.92	10	20	50	70	H20
MMD835-	15	0.48	0.98	10	20	50	70	T86
		0.36 0.86	0.86					0805-2

Test Conditions: V_B : $I_R = 10 \mu A$

 C_T : $V_R = 6 \text{ V}$, 1 MHz t: $I_F = 10 \text{ mA}$, $I_R = 6 \text{ mA}$ @ 50% Recovery t_t: for MMD805 - MMD840: $I_F = 10 \text{ mA}$, $V_R = 10 \text{ V}$

 t_t : for MMDB30 - MMDB45: I_F = 3 mA, V_R = 7 V

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Rev. V5

Ceramic Packaged Electrical Specifications: T_A = 25°C

Model	Voltage Breakdown (V _B)	Capac	tal :itance ⊱ _T)	Lifetime (t)		Transition Time (t _t)		Package
	٧	р	F	r	ns		ps	
	Min.	Min.	Max.	Min.	Тур.	Тур.	Max.	
		0.28	0.48		10			E28 / 28X
MMD007	20	0.32	0.52	_		50	70	H27
MMD837-	20	0.38	0.58	5				T86
		0.26	0.46	=				805-2
		0.28	0.48	7	15	50	70	E28 / 28X
MMD040	45	0.32	0.52					H27
MMD840-	15	0.38	0.58					T86
		0.26	0.46	=				0805-2
		0.23	0.33		4	30	38	E28 / 28X
MMDB30-	14	0.20	0.30	1				0402
		0.21	0.31					0805-2
		0.21	0.28					E28 / 28X
MMDB35-	16	0.18	0.22	1	4	35	45	0402
		0.19	0.26					0805-2
		0.19	0.28			45		E28 / 28X
MMDB45-	25	0.16	0.25	3	8		58	0402
		0.17	0.26					0805-2

Test Conditions: $V_B: I_R = 10 \mu A$

 C_{T} : $V_R = 6$ V, 1 MHz t: $I_F = 10$ mA, $I_R = 6$ mA @ 50% Recovery t_t: for MMD805 - MMD840: $I_F = 10$ mA, $V_R = 10$ V t_t: for MMDB30 - MMDB45: $I_F = 3$ mA, $V_R = 7$ V

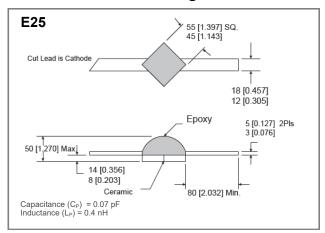
Absolute Maximum Ratings

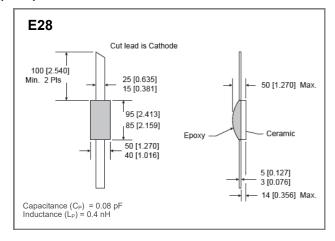
Parameters	Rating				
Reverse Voltage	Rated V _{BR}				
Forward Current	MMD = 150 mA MMDB = 50 mA				
Operating / Storage Temperature	-65°C to +175°C				
Mounting / Bonding Temperature	+260°C peak per JEDEC J-STD-20C				

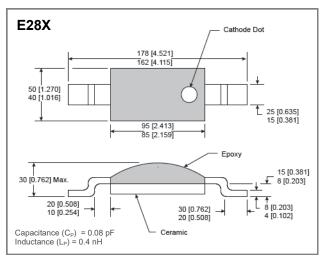


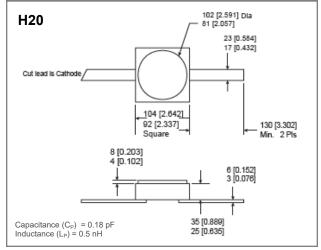
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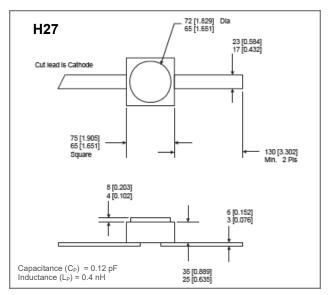
Ceramic Outline Drawings: Dimension = mils (mm)









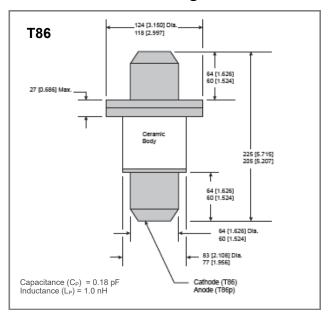


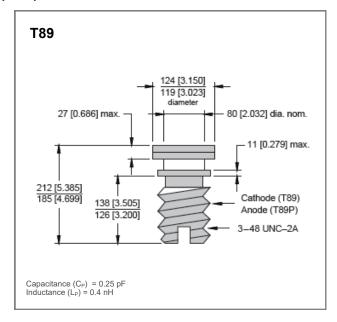
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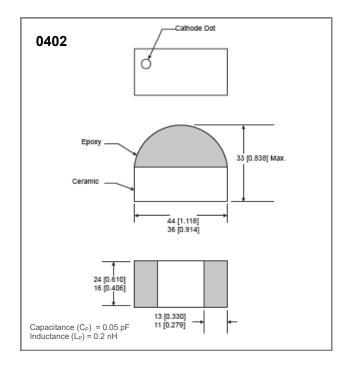


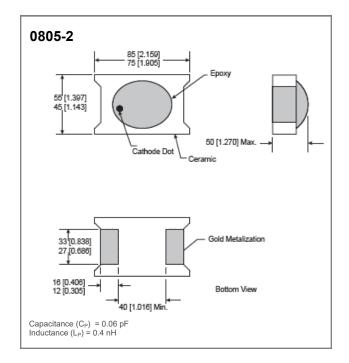
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Ceramic Outline Drawings: Dimension = mils (mm)











Rev. V5

Glass Packaged Electrical Specifications: T_A = 25°C

Model # (-package)	Voltage Breakdown (V _B)	Total Capacitance (C _T)		reakdown Capacitance (t)		Tran Ti (Package	
	V	pF		n	ns		ps	
	Min.	Тур.	Max.	Min.	Тур.	Тур.	Max.	
MMD0151-	15	0.70	0.80	10	15	100	_	
MMD0153-	25	0.45	0.55	10	15	95	_	
MMD0803-	70	4.15	6.15	200	250	275	400	
MMD0815-	50	3.15	4.15	100	135	180	320	A15
MMD0825-	45	1.15	2.15	30	50	130	160	
MMD0833-	25	1.75	1.80	10	15	90	_	
MMD0840-	15	0.60	0.75	10	20	75	_	

Test Conditions:

 $V_B: I_R = 10 \mu A$

 C_T : for MMD0151 & MMD0153: V_R = 6 V, 1 MHz C_T : for MMD0803 - MMD0840: V_R = 10 V, 1 MHz

t: I_F = 10 mA, I_R = 6 mA @ 50% Recovery

 t_t : for MMD0803 - MMD0825: I_F = 10 mA, V_R = 10 V

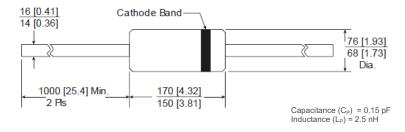
 t_t : for MMD0151, MMD0153, MMD0833, MMD0840: chip data packaged limits to 100 ps

Absolute Maximum Ratings

Parameters	Rating			
Reverse Voltage	Rated V _{BR}			
Forward Current	100 mA			
Thermal Resistance, Junction to Case	+600°C/W			
Operating / Storage Temperature	-65°C to +200°C			
Mounting / Bonding Temperature	+230°C for 10 seconds			

Glass Outline Drawing

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Plastic Packaged Electrical Specifications: T_A = 25°C

Model	Voltage Breakdown (V _B)	n Capacitance (C _J)		Lifetime (t)		Transition Time (t _t)		Package	
	V	pF		ns		ps			
	Min.	Min.	Max.	Min.	Тур.	Тур.	Max.		
SMMD805-	60	2.5	3.5	80	100	250	300	SOT23 (-0S, -1S)	
								SOD323	
SMMD810-	50	1.5	2.5	40	70	200	250	SOT23 (-0S, -1S)	
SIVIIVID610-	50	1.5	2.5	40	70	200	250	SOD323	
SMMD820-	40	1.0	1.7	30	60	110	125	SOT23 (-0S, -1S)	
SIVIIVID020-	40	1.0	1.7	30	00	110	123	SOD323	
SMMD830-	25	0.5	1.0	15	30	90	110	SOT23 (-0S, -1S)	
SIVIIVID030-	25	0.5	1.0	15	30	90	110	SOD323	
								SOT23 (-0S, -1S)	
SMMD832-	20	0.4	0.8	10	20	85	100	SOD323	
								SC79 (SOD523)*	
SMMD835-	20	0.3	0.7	10	15	80	100	SOT23 (-0S, -1S)	
SIVIIVID633-	20	0.3	0.7	10	15	80	100	SOD323	
SMMD837-	20	0.2	0.4	5	12	75	90	SOT23 (-0S, -1S)	
SivilviDo31-	20	0.2	0.4	3	12	13	90	SOD323	
SMMD840-	15	0.2	0.4	5	10	70	90	SOT23 (-0S, -1S)	
SivilviD0+0-	10	0.2	0.4	, ,	10	70	30	SOD323	

Test Conditions: $V_B: I_R = 10 \mu A$

 C_J : $V_R = 6 \dot{V}$, 1 MHz

t: I_F = 10 mA, I_R = 6 mA @ 50% Recovery

* MAVR-011057-12790T

 $V_B{:}~I_R$ @ 10 μA = 20 V min. Ct: V_R @ 6 V, 1 MHz = 0.75 pF max.

TI: If @ 10 mA, I_R @ 6 mA @ 50% Recovery = 10 ns typ.

Absolute Maximum Ratings

<u></u>							
Parameters	Rating						
Reverse Voltage	Rated V _{BR}						
Forward Current	100 mA						
Power Dissipation	250 mW, derate linearly to zero @ T _A = +150°C						
Operating / Storage Temperature	-65°C to +150°C						
Mounting / Bonding Temperature	+260°C peak per JEDEC J-STD-20C						

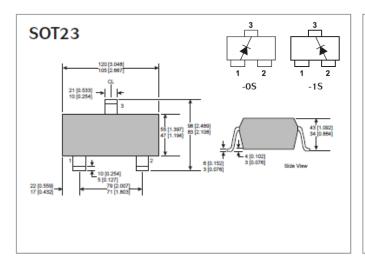
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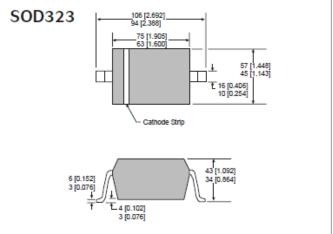
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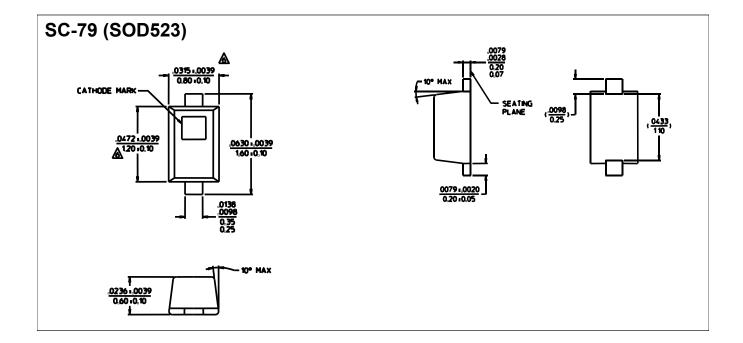


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Plastic Outline Drawings









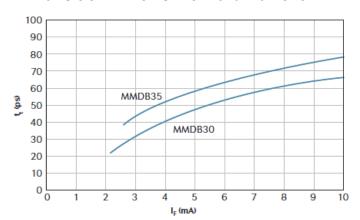
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Typical Performance Curves: T_A = 25°C

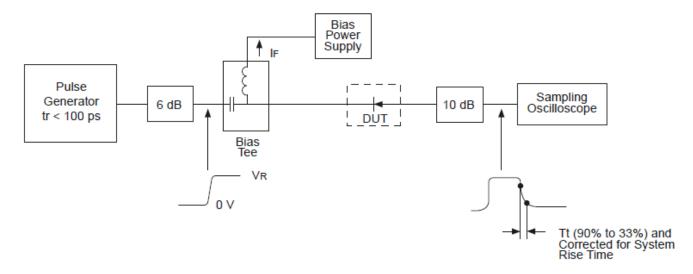
Transition Time vs. Drive

810 $\tau = 86ns$ 100 $\tau = 78 \text{ns}$ 820 t, (ps) $\tau = 30$ ns 830 $\tau = 18 \text{ns}$ 835 50 840 $\tau = 13ns$ 200 400 600 800 1000 1200 1400 1600 1800 Drive (pC)

Transition Time vs. Forward Current



Transition Time Test Circuit



Silicon Step Recovery Diodes



MMDx & SMMDx Series

Rev. V5

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